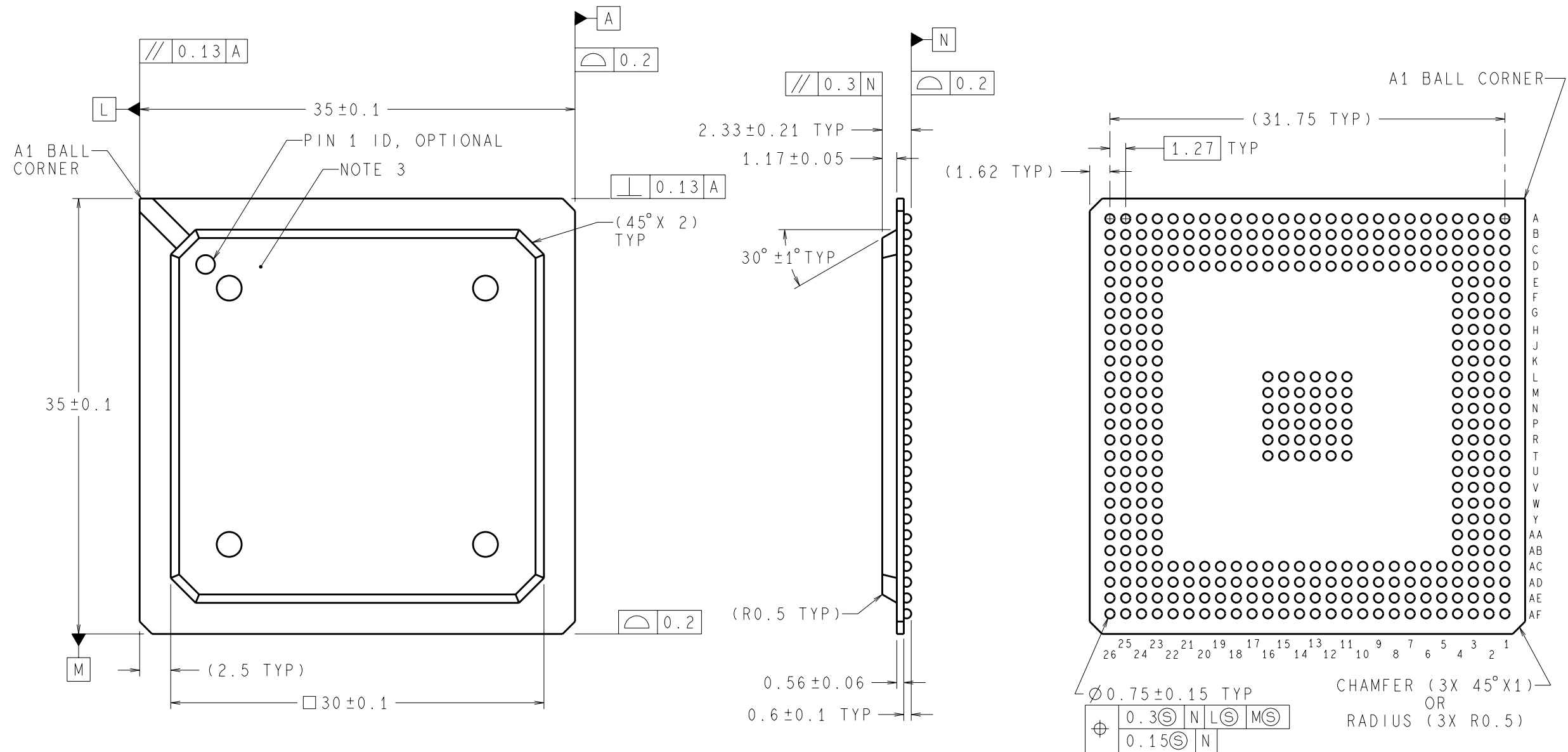


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11633	12/20/1996	TL/SM
B	REVISE SUBSTR CORNERS, BODY CHAMFERS & TOL; ADD EJECTOR PINS TO BODY	11708	10/02/1997	TL/SL
C	REVISE DWG PER MARKUP INPUT.	11934	02/12/1998	MS/AC
D	ADD OR RADIUS (3X R0.5); REVISE NOTES 3 & 4; BALL POS. TOL. $\varnothing 0.15$ WAS $\varnothing 0.1$.	182	03/08/2001	MS/CD



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION AND MOLD EJECTOR PIN MARKS AT EACH CORNER OF MOLDED PACKAGE SURFACE.
- REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH.

APPROVALS	DATE	National Semiconductor			
DRAWN T. LEQUANG	12/20/1996	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DFTG. CHK. THANH LEQUANG	03/08/2001	PBGA, 35 X 35 X 2.33mm, 388 BALL, 1.27mm PITCH			
ENGR. CHK. CORNEL DEVERA	03/08/2001				
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UCB388A	D
DO NOT SCALE DRAWING				SHEET 1 of 1	